

Circuit Pitfalls

On how to avoid bad circuit design!

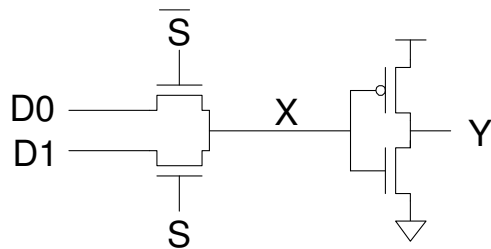
Outline

- Circuit Pitfalls
 - Detective puzzle
 - Given circuit and symptom, diagnose cause and recommend solution
 - All these pitfalls have caused failures in real chips
- Noise Budgets
- Reliability

Bad Circuit 1

- Circuit

- 2:1 multiplexer



Principle:

Solution:

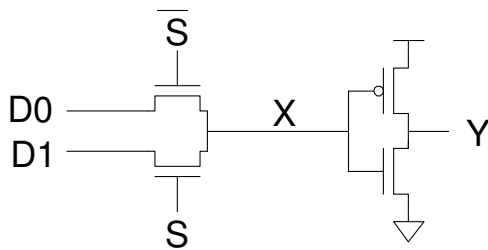
- Symptom

- Mux works when selected D is 0 but not 1.
- Or fails at low V_{DD} .

Bad Circuit 1

- Circuit

- 2:1 multiplexer



- Symptom

- Mux works when selected
D is 0 but not 1.
- Or fails at low V_{DD} .

Principle: Threshold drop

X never rises above $V_{DD} - V_t$

V_t is raised by the body effect

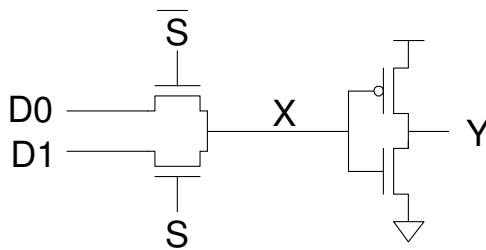
The threshold drop is most serious as V_t becomes a greater fraction of V_{DD} .

Solution:

Bad Circuit 1

- Circuit

- 2:1 multiplexer



- Symptom

- Mux works when selected D is 0 but not 1.
- Or fails at low V_{DD} .
- Or fails in SFSF corner.

Principle: Threshold drop

X never rises above $V_{DD} - V_t$

V_t is raised by the body effect

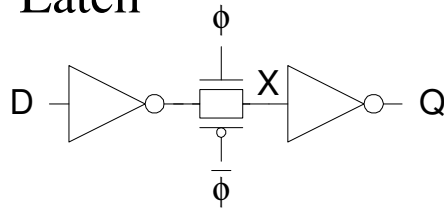
The threshold drop is most serious as V_t becomes a greater fraction of V_{DD} .

Solution: Use transmission gates, not pass transistors

Bad Circuit 2

- Circuit

- Latch



Principle:

Solution:

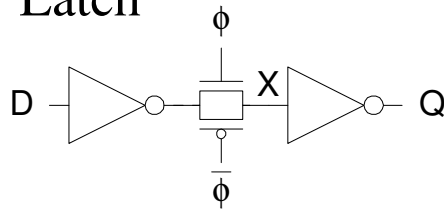
- Symptom

- Load a 0 into Q
- Set $\phi = 0$
- Eventually Q spontaneously flips to 1

Bad Circuit 2

- Circuit

- Latch



- Symptom

- Load a 0 into Q
- Set $\phi = 0$
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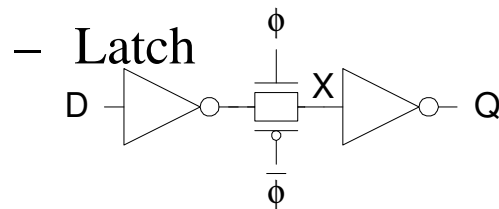
Principle: Leakage

X is a dynamic node holding value as charge on the node
Eventually subthreshold leakage may disturb charge

Solution:

Bad Circuit 2

- Circuit



- Symptom

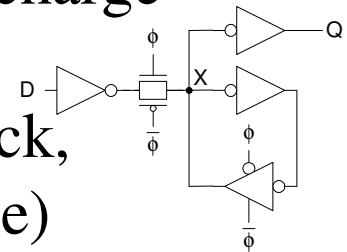
- Load a 0 into Q
- Set $\phi = 0$
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Principle: Leakage

X is a dynamic node holding value as charge on the node
Eventually subthreshold leakage may disturb charge

Solution: Staticize node with feedback

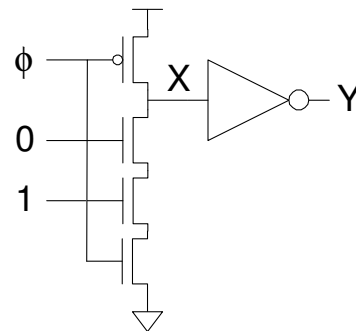
Or periodically refresh node (requires fast clock,
not practical for processes with big leakage)



Bad Circuit 3

- Circuit

- Domino AND gate



Principle:

Solution:

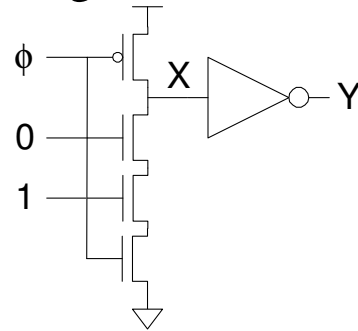
- Symptom

- Precharge gate ($Y=0$)
- Then evaluate
- Eventually Y spontaneously flips to 1

Bad Circuit 3

- Circuit

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- Symptom

- Precharge gate ($Y=0$)
 - Then evaluate
 - Eventually Y spontaneously flips to 1

Principle: Leakage

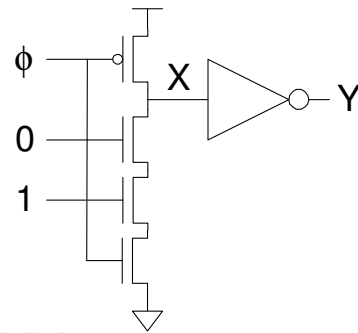
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Solution:

Bad Circuit 3

- Circuit

- Domino AND gate



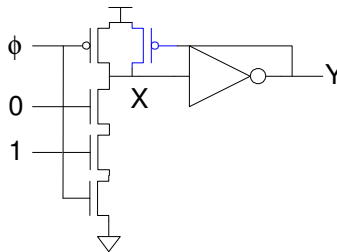
- Symptom

- Precharge gate ($Y=0$)
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Principle: Leakage

X is a dynamic node holding value as charge on the node
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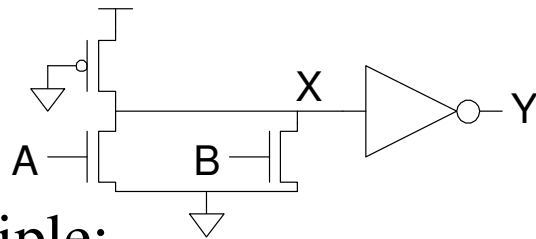
Solution: Keeper



Bad Circuit 4

- Circuit

- Pseudo-nMOS OR



Principle:

Solution:

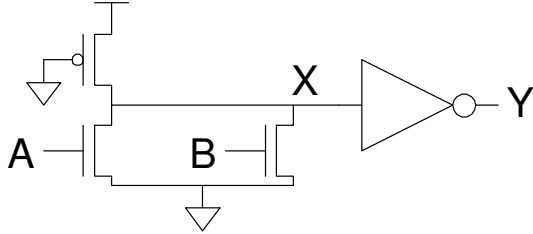
- Symptom

- When only one input is true, $Y = 0$.

Bad Circuit 4

- Circuit

- Pseudo-nMOS OR



- Symptom

- When only one input is true, $Y = 0$.

Principle: Ratio Failure

nMOS and pMOS fight each other.

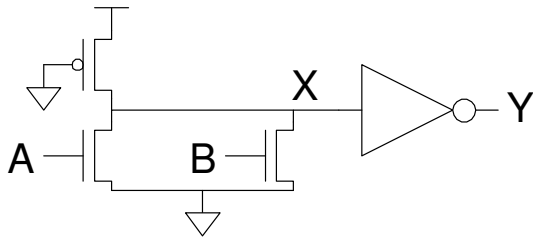
If the pMOS is too strong, nMOS cannot pull X low enough.

Solution:

Bad Circuit 4

- Circuit

- Pseudo-nMOS OR



- Symptom

- When only one input is true, $Y = 0$.

Principle: Ratio Failure

nMOS and pMOS fight each other.

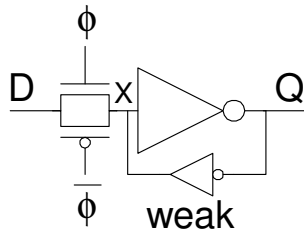
If the pMOS is too strong, nMOS cannot pull X low enough.

Solution: Check that ratio is satisfied in all corners

Bad Circuit 5

- Circuit

- Latch



Principle:

Solutions:

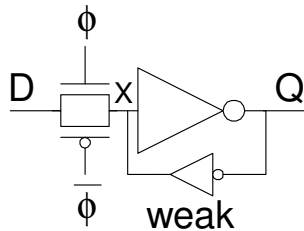
- Symptom

- Q stuck at 1.
- May only happen for certain latches where input is driven by a small gate located far away.

Bad Circuit 5

- Circuit

- Latch



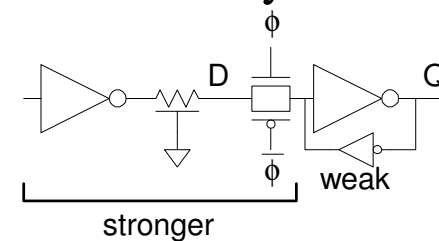
Principle: Ratio Failure (again)

Series resistance of D driver, wire resistance, and t_{gate} must be much less than weak feedback inverter.

Solutions:

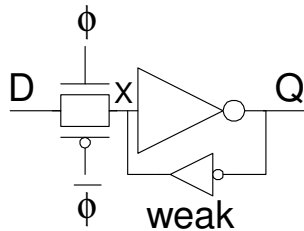
- Symptom

- Q stuck at 1.
- May only happen for certain latches where input is driven by a small gate located far away.



Bad Circuit 5

- Circuit
 - Latch



Principle: Ratio Failure (again)

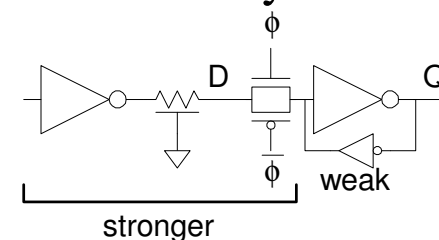
Series resistance of D driver, wire resistance, and t_{gate} must be much less than weak feedback inverter.

Solutions: Check relative strengths

Avoid unbuffered diffusion inputs where driver is unknown

- Symptom

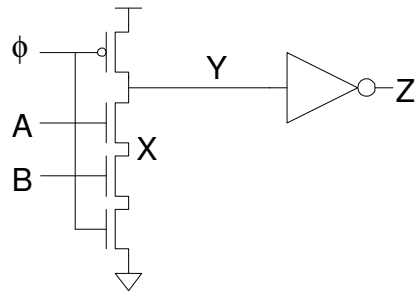
- Q stuck at 1.
- May only happen for certain latches where input is driven by a small gate located far away.



Bad Circuit 6

- Circuit

- Domino AND gate



Principle:

Solutions:

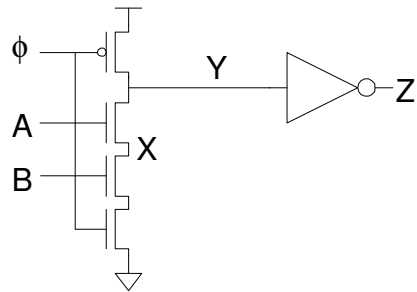
- Symptom

- Precharge gate while $A = B = 0$, so $Z = 0$
- Set $\phi = 1$
- A rises
- Z is observed to sometimes rise

Bad Circuit 6

- Circuit

- Domino AND gate



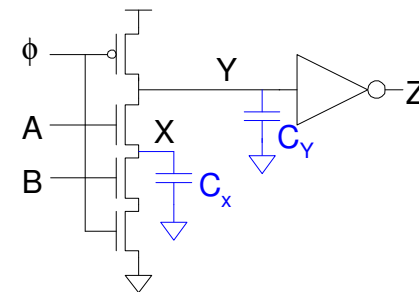
Principle: Charge Sharing

If X was low, it shares charge with Y

Solutions:

- Symptom

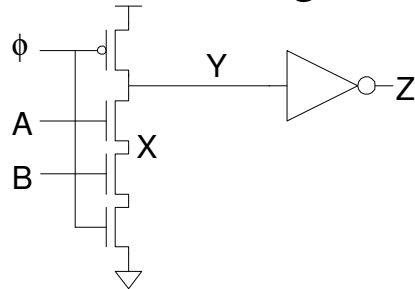
- Precharge gate while $A = B = 0$, so $Z = 0$
- Set $\phi = 1$
- A rises
- Z is observed to sometimes rise



Bad Circuit 6

- Circuit

- Domino AND gate



Principle: Charge Sharing

If X was low, it shares charge with Y

Solutions: Limit charge sharing

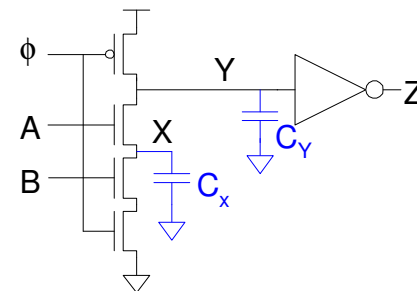
$$V_x = V_Y = \frac{C_Y}{C_x + C_Y} V_{DD}$$

Safe if $C_Y \gg C_X$

Or precharge node X too

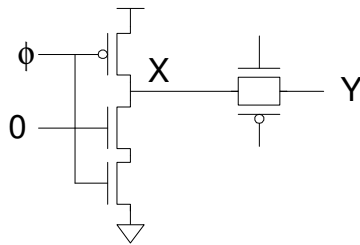
- Symptom

- Precharge gate while $A = B = 0$, so $Z = 0$
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- A rises
- Z is observed to sometimes rise



Bad Circuit 7

- Circuit
 - Dynamic gate + latch



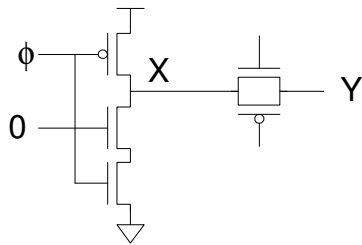
Principle:

Solution:

- Symptom
 - Precharge gate while transmission gate latch is opaque
 - Evaluate
 - When latch becomes transparent, X falls

Bad Circuit 7

- Circuit
 - Dynamic gate + latch



Principle: Charge Sharing

If Y was low, it shares charge with X

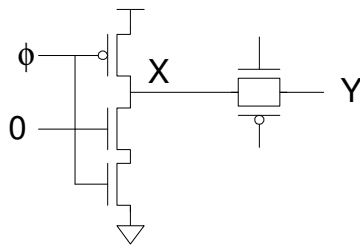
Solution:

- Symptom
 - Precharge gate while transmission gate latch is opaque
 - Evaluate
 - When latch becomes transparent, X falls

Bad Circuit 7

- Circuit

- Dynamic gate + latch



- Symptom

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Principle: Charge Sharing

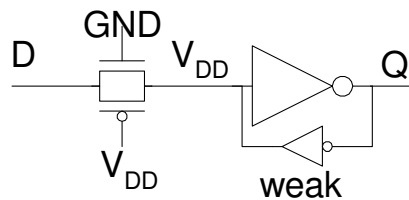
If Y was low, it shares charge with X

Solution: Buffer dynamic nodes before driving transmission gate

Bad Circuit 8

- Circuit

- Latch



- Symptom

- Q changes while latch is opaque
- Especially if D comes from a far-away driver

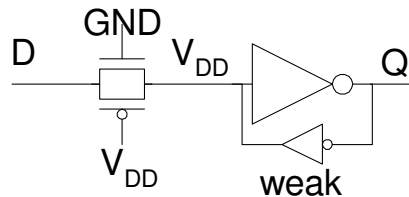
Principle:

Solution:

Bad Circuit 8

- Circuit

- Latch



- Symptom

- Q changes while latch is opaque
- Especially if D comes from a far-away driver

Principle: Diffusion Input Noise Sensitivity

If $D < -V_t$, transmission gate turns on

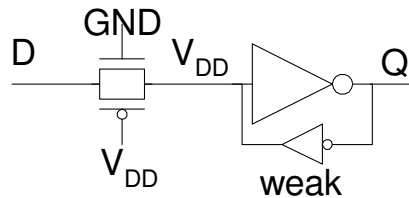
Most likely because of power supply noise or coupling on D

Solution:

Bad Circuit 8

- Circuit

- Latch



- Symptom

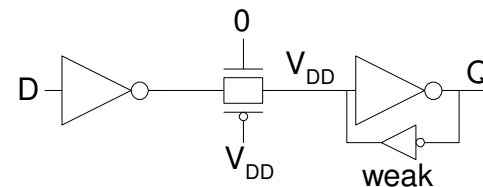
- Q changes while latch is opaque
- Especially if D comes from a far-away driver

Principle: Diffusion Input Noise Sensitivity

If $D < -V_t$, transmission gate turns on

Most likely because of power supply noise or coupling on D

Solution: Buffer D locally



Bad Circuit 9

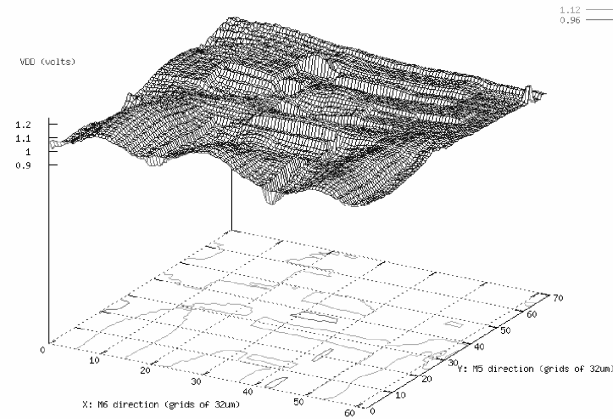
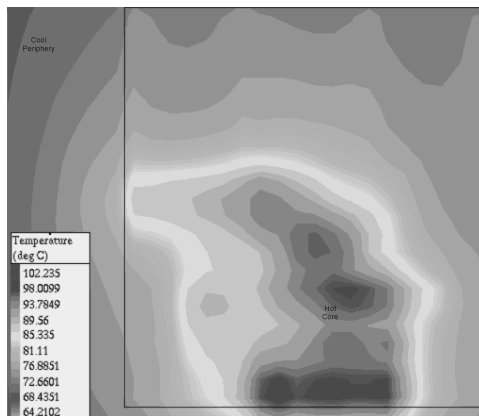
- Circuit
 - Anything
- Symptom
 - Some gates are slower than expected

Principle:

Bad Circuit 9

- Circuit
 - Anything
- Symptom
 - Some gates are slower than expected

Principle: Hot Spots and Power Supply Noise

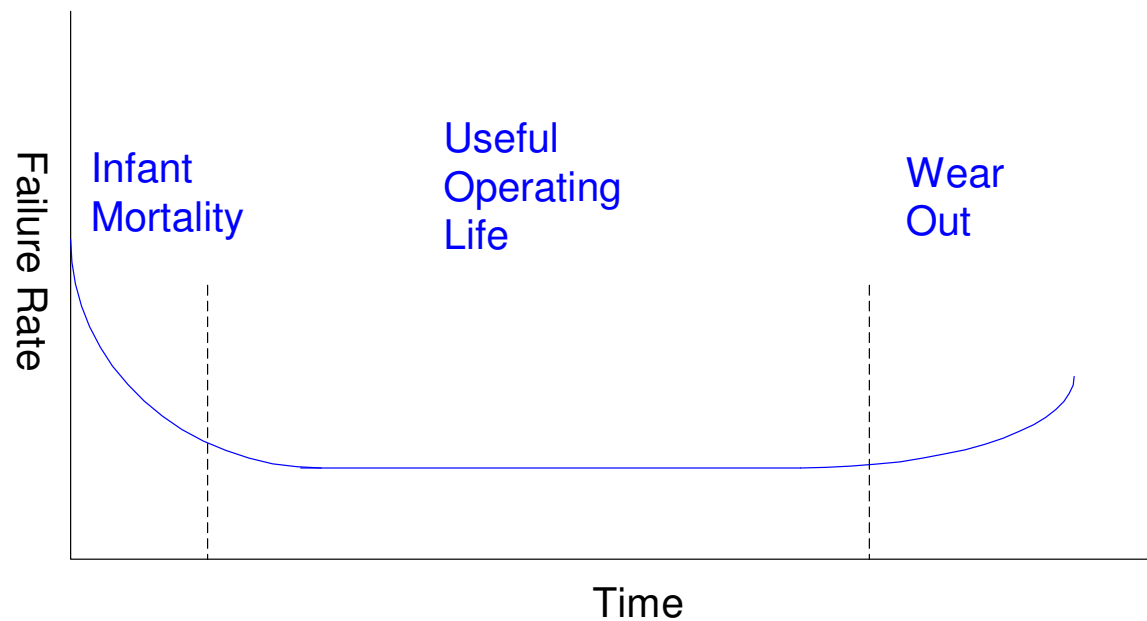


Noise

- Sources
 - Power supply noise / ground bounce
 - Capacitive coupling
 - Charge sharing
 - Leakage
 - Noise feedthrough
- Consequences
 - Increased delay (for noise to settle out)
 - Or incorrect computations

Reliability

- Hard Errors
- Soft Errors



Electromigration

- “Electron wind” causes movement of metal atoms along wires
- Excessive electromigration leads to open circuits
- Most significant for unidirectional (DC) current
 - Depends on current density J_{dc} (current / area)
 - Exponential dependence on temperature
 - Black’s Equation:
$$MTTF \propto \frac{e^{\frac{E_a}{kT}}}{J_{dc}^n}$$
 - Typical limits: $J_{dc} < 1 - 2 \text{ mA} / \mu\text{m}^2$

Self-Heating

- Current through wire resistance generates heat
 - Oxide surrounding wires is a thermal insulator
 - Heat tends to build up in wires
 - Hotter wires are more resistive, slower
- Self-heating limits AC current densities for reliability

$$I_{rms} = \sqrt{\frac{\int_0^T I(t)^2 dt}{T}}$$

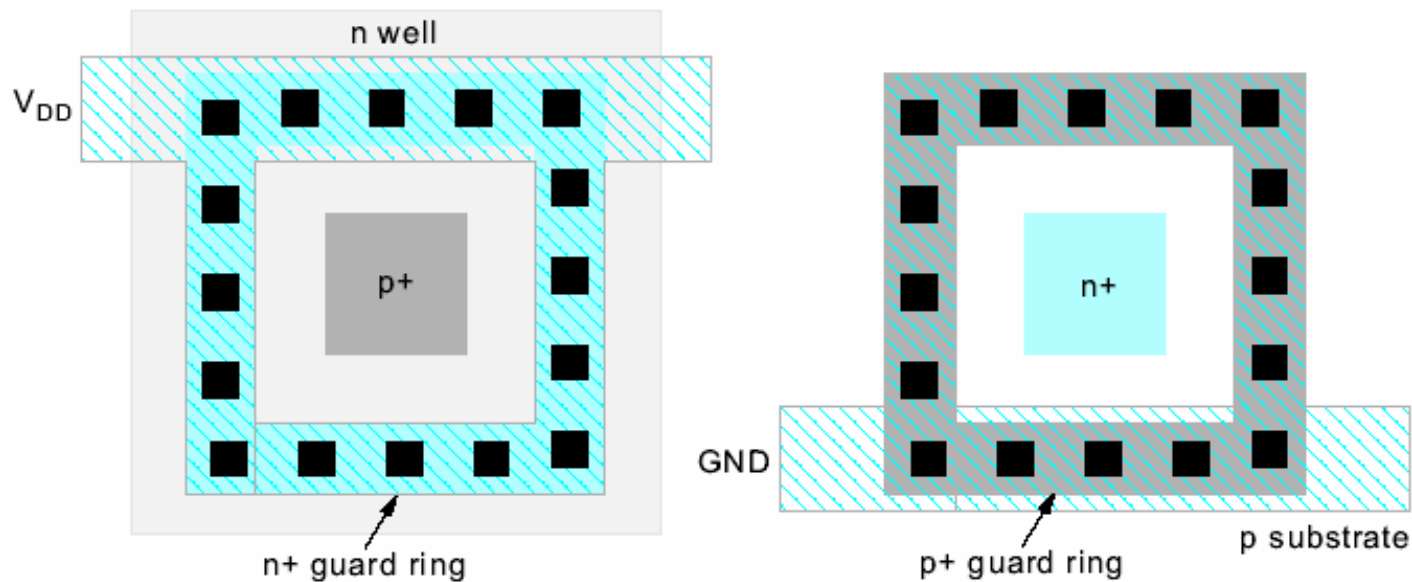
- Typical limits: $J_{rms} < 15 \text{ mA} / \mu\text{m}^2$

Hot Carriers

- Electric fields across channel impart high energies to some carriers
 - These “hot” carriers may be blasted into the gate oxide where they become trapped
 - Accumulation of charge in oxide causes shift in V_t over time
 - Eventually V_t shifts too far for devices to operate correctly
- Choose V_{DD} to achieve reasonable product lifetime
 - Worst problems for inverters and NORs with slow input rise time and long propagation delays

Guard Rings

- Latchup risk greatest when diffusion-to-substrate diodes could become forward-biased
- Surround sensitive region with guard ring to collect injected charge



Overvoltage

- High voltages can damage transistors
 - Electrostatic discharge
 - Oxide arcing
 - Punchthrough
 - Time-dependent dielectric breakdown (TDDB)
 - Accumulated wear from tunneling currents
- Requires low V_{DD} for thin oxides and short channels
- Use ESD protection structures where chip meets real world

Summary

- Static CMOS gates are very robust
 - Will settle to correct value if you wait long enough
- Other circuits suffer from a variety of pitfalls
 - Tradeoff between performance & robustness
- Very important to check circuits for pitfalls
 - For large chips, you need an automatic checker.
 - Design rules aren't worth the paper they are printed on unless you back them up with a tool.

Soft Errors

- In 1970's, DRAMs were observed to occasionally flip bits for no apparent reason
 - Ultimately linked to alpha particles and cosmic rays
- Collisions with particles create electron-hole pairs in substrate
 - These carriers are collected on dynamic nodes, disturbing the voltage
- Minimize soft errors by having plenty of charge on dynamic nodes
- Tolerate errors through ECC, redundancy
- Soft errors are now a problem for logic too!